

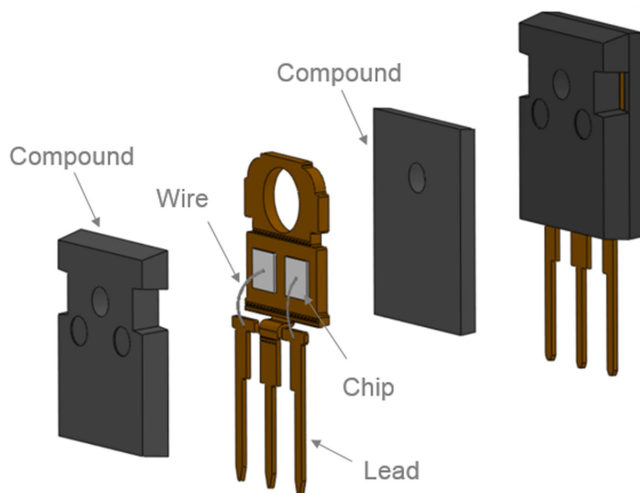
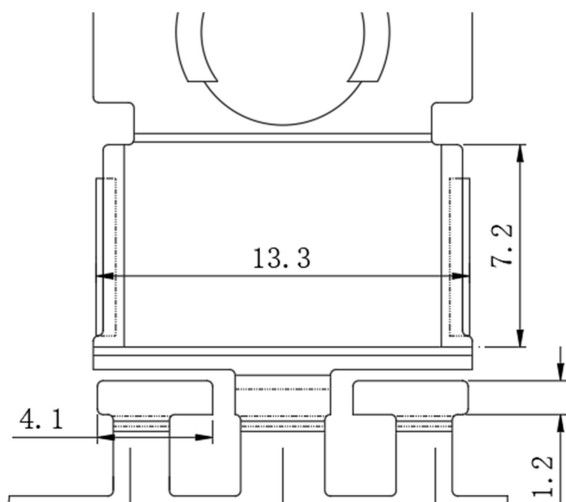
TO-247S-AB

TO-247S-AC

## 1: Certification

- System:
  - IATF 16949
  - ISO9001
  - ISO14001
  - ISO45001
- ROHS/REACH/ELV:
  - Lead frame、Wire, Molding compound、Post plating.
- UL 94: V-0
- Whisker Test: JESD 201 class 1A
- AEC-Q101 (Rev E): Qualified Available
- Solder bath temperature : 275°C maximum, 10 s

## 2: Internal Structure Diagram



### Meet Die Size

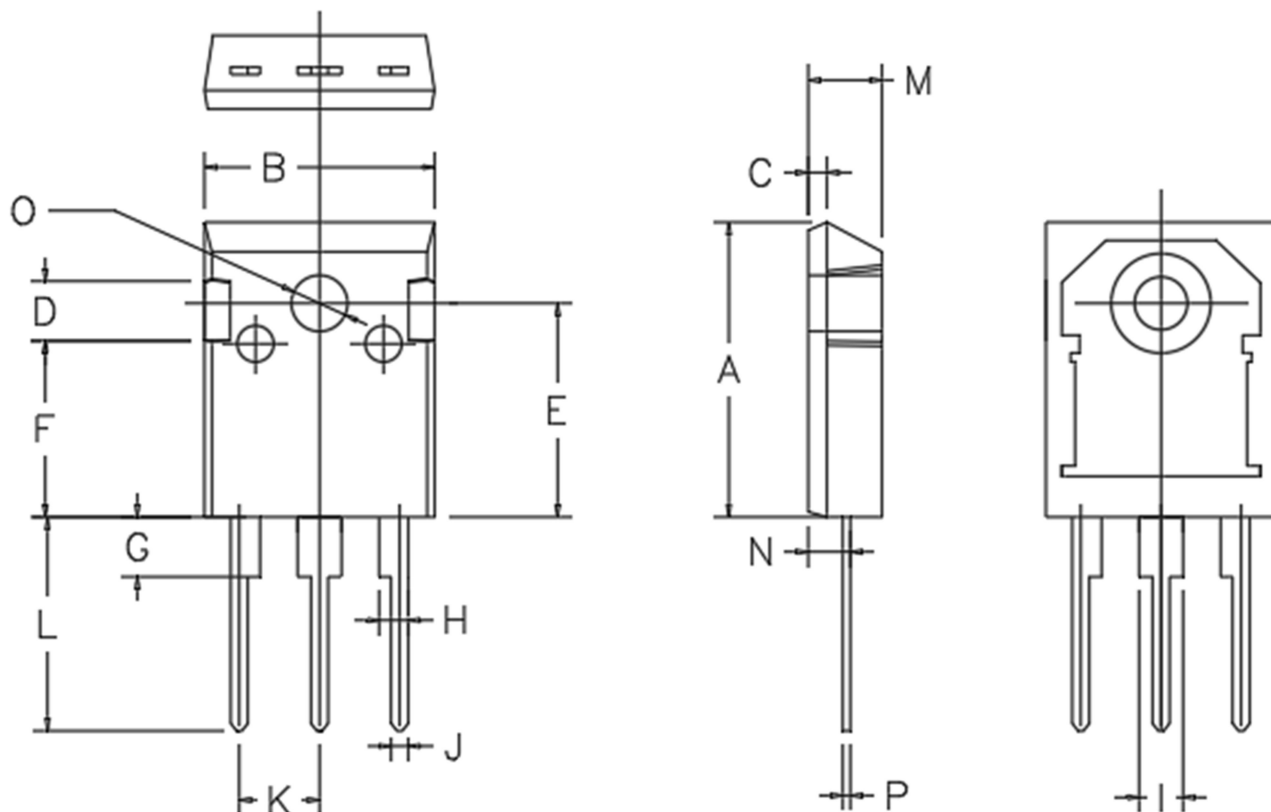
Die Pad(mm)	Die size(mm)	
X=11.30, Y=7.30	Double die (Max)	Single die(Max)
	X=4.90, Y=6.95	X=10.30, Y=6.95

## 3: Reliability Experiment

	Test	Test Condition
1	Temperature Cycle (TMCL)	500 cycles at -55°C to 150°C
2	Unbiased Highly Accelerated Stress Test (UHST)	96 hours at Ta = 130°C, RH = 85% ;P=2.27atm.
3	High Temperature, Humidity & Reverse Bias (THBS)	1000 hours at Tj = 85°C, RH = 85%, Reverse Bias = 80% rated voltage
4	Thermal Fatigue (TFAT)	10000 cycles, Tj = 25°C to 125°C, DTj ≥ 80°C, Id=depends on device & Ton = Toff ~2.5 to 3.5 mins.
5	Static High Temperature Life (SHTL)	1000 hours – Tj = max operating temp, Reverse Bias = 80% / 100% rated voltage.(according to customer request).
6	High Temperature Storage (HTSL)	1000 hours at Ta = 150°C or Ta=175°C

## 4: Package Outline Dimensions in millimeters

### 4.1 POD



DIM	MILLIMETERS		DIM	MILLIMETERS	
	MIN.	MAX.		MIN.	MAX.
A	19.80	20.20	I	2.80	3.20
B	15.45	15.75	J	1.05	1.35
C	0.95	1.25	K	5.25	5.65
D	3.85	4.15	L	14.00	14.60
E	14.25	14.55	M	4.75	5.15
F	11.70	12.10	N	2.30	2.60
G	3.80	4.20	O	3.50	3.90
H	1.80	2.20	P	0.38	0.62